

74HC138; 74HCT138

3-to-8 line decoder/demultiplexer; inverting

Rev. 4 — 27 June 2012

Product data sheet

1. General description

The 74HC138; 74HCT138 is a high-speed Si-gate CMOS device and is pin compatible with Low-power Schottky TTL (LSTTL).

The 74HC138; 74HCT138 decoder accepts three binary weighted address inputs (A_0 , A_1 and A_2) and when enabled, provides 8 mutually exclusive active LOW outputs (\overline{Y}_0 to \overline{Y}_7).

The 74HC138; 74HCT138 features three enable inputs: two active LOW (\overline{E}_1 and \overline{E}_2) and one active HIGH (E_3). Every output is HIGH unless \overline{E}_1 and \overline{E}_2 are LOW and E_3 is HIGH.

This multiple enable function allows easy parallel expansion of the 74HC138; 74HCT138 to a 1-of-32 (5 lines to 32 lines) decoder with just four 74HC138; 74HCT138 ICs and one inverter.

The 74HC138; 74HCT138 can be used as an eight output demultiplexer by using one of the active LOW enable inputs as the data input and the remaining enable inputs as strobes. Permanently tie unused enable inputs to their appropriate active HIGH- or LOW-state.

The 74HC138; 74HCT138 is identical to the 74HC238; 74HCT238 but has inverting outputs.

2. Features and benefits

- Demultiplexing capability
- Multiple input enable for easy expansion
- Complies with JEDEC standard no. 7A
- Ideal for memory chip select decoding
- Active LOW mutually exclusive outputs
- ESD protection:
 - ◆ HBM EIA/JESD22-A114F exceeds 2000 V
 - ◆ MM EIA/JESD22-A115-A exceeds 200 V
- Multiple package options
- Specified from $-40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$ and from $-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$

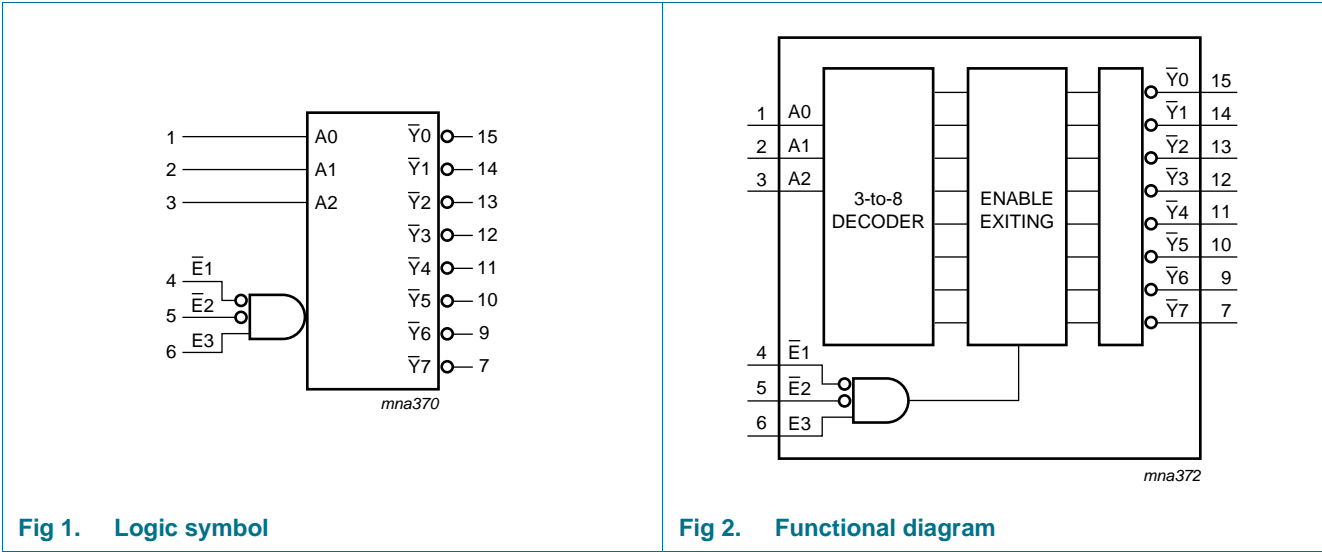


3. Ordering information

Table 1. Ordering information

Type number	Package			
	Temperature range	Name	Description	Version
74HC138N	−40 °C to +125 °C	DIP16	plastic dual in-line package; 16 leads (300 mil)	SOT38-4
74HCT138N				
74HC138D	−40 °C to +125 °C	SO16	plastic small outline package; 16 leads; body width 3.9 mm	SOT109-1
74 HCT138D				
74HC138DB	−40 °C to +125 °C	SSOP16	plastic shrink small outline package; 16 leads; body width 5.3 mm	SOT338-1
74HCT138DB				
74HC138PW	−40 °C to +125 °C	TSSOP16	plastic thin shrink small outline package; 16 leads; body width 4.4 mm	SOT403-1
74HCT138PW				
74HC138BQ	−40 °C to +125 °C	DHVQFN16	plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 16 terminals; body 2.5 × 3.5 × 0.85 mm	SOT763-1
74HCT138BQ				

4. Functional diagram



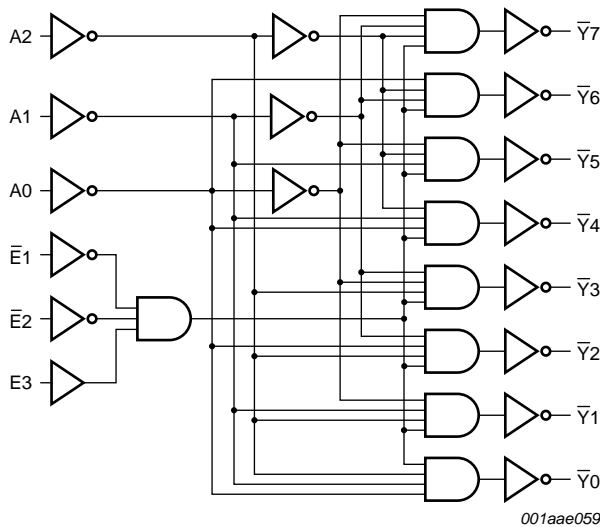


Fig 3. Logic diagram

5. Pinning information

5.1 Pinning

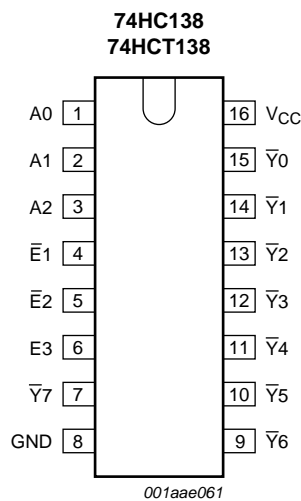
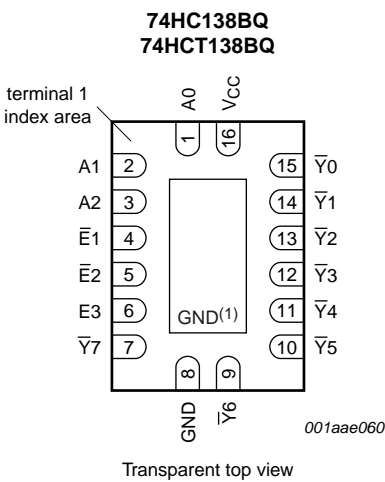


Fig 4. Pin configuration DIP16, SO16, SSOP16 and TSSOP16



- (1) The die substrate is attached to this pad using conductive die attach material. It cannot be used as supply pin or input.

Fig 5. Pin configuration DHVQFN16

5.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
A0, A1, A2	1, 2, 3	address input A0, A1, A2
$\bar{E}1, \bar{E}2$	4, 5	enable input $\bar{E}1, \bar{E}2$ (active LOW)
E3	6	enable input E3 (active HIGH)
$\bar{Y}0, \bar{Y}1, \bar{Y}2, \bar{Y}3, \bar{Y}4, \bar{Y}5, \bar{Y}6, \bar{Y}7$	15, 14, 13, 12, 11, 10, 9, 7	output $\bar{Y}0, \bar{Y}1, \bar{Y}2, \bar{Y}3, \bar{Y}4, \bar{Y}5, \bar{Y}6, \bar{Y}7$ (active LOW)
GND	8	ground (0 V)
V _{CC}	16	positive supply voltage

6. Functional description

Table 3. Function table^[1]

Control			Input			Output							
$\bar{E}1$	$\bar{E}2$	E3	A2	A1	A0	$\bar{Y}7$	$\bar{Y}6$	$\bar{Y}5$	$\bar{Y}4$	$\bar{Y}3$	$\bar{Y}2$	$\bar{Y}1$	$\bar{Y}0$
H	X	X	X	X	X	H	H	H	H	H	H	H	H
X	H	X											
X	X	L											
L	L	H	L	L	L	H	H	H	H	H	H	H	L
			L	L	H	H	H	H	H	H	H	L	H
			L	H	L	H	H	H	H	H	L	H	H
			L	H	H	H	H	H	H	L	H	H	H
			H	L	L	H	H	H	L	H	H	H	H
			H	L	H	H	H	L	H	H	H	H	H
			H	H	L	H	L	H	H	H	H	H	H
			H	H	H	L	H	H	H	H	H	H	H

- [1] H = HIGH voltage level;
 L = LOW voltage level;
 X = don't care.

7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
V _{CC}	supply voltage		-0.5	+7	V
I _{IK}	input clamping current	V _I < -0.5 V or V _I > V _{CC} + 0.5 V	-	±20	mA
I _{OK}	output clamping current	V _O < -0.5 V or V _O > V _{CC} + 0.5 V	-	±20	mA
I _O	output current	V _O = -0.5 V to (V _{CC} + 0.5 V)	-	±25	mA
I _{CC}	quiescent supply current		-	50	mA
I _{GND}	ground current		-	-50	mA
T _{stg}	storage temperature		-65	+150	°C

Table 4. Limiting values ...continued

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
P _{tot}	total power dissipation				
	DIP16 package		[1] -	750	mW
	SO16 package		[2] -	500	mW
	SSOP16 package		[3] -	500	mW
	TSSOP16 package		[3] -	500	mW
	DHVQFN16 package		[4] -	500	mW

[1] For DIP16 package: P_{tot} derates linearly with 12 mW/K above 70 °C.[2] For SO16 package: P_{tot} derates linearly with 8 mW/K above 70 °C.[3] For SSOP16 and TSSOP16 packages: P_{tot} derates linearly with 5.5 mW/K above 60 °C.[4] For DHVQFN16 packages: P_{tot} derates linearly with 4.5 mW/K above 60 °C.

8. Recommended operating conditions

Table 5. Recommended operating conditions

Voltages are referenced to GND (ground = 0 V)

Symbol	Parameter	Conditions	74HC138			74HCT138			Unit
			Min	Typ	Max	Min	Typ	Max	
V _{CC}	supply voltage		2.0	5.0	6.0	4.5	5.0	5.5	V
V _I	input voltage		0	-	V _{CC}	0	-	V _{CC}	V
V _O	output voltage		0	-	V _{CC}	0	-	V _{CC}	V
T _{amb}	ambient temperature		-40	+25	+125	-40	+25	+125	°C
Δt/ΔV	input transition rise and fall rate	V _{CC} = 2.0 V	-	-	625	-	-	-	ns/V
		V _{CC} = 4.5 V	-	1.67	139	-	1.67	139	ns/V
		V _{CC} = 6.0 V	-	-	83	-	-	-	ns/V

9. Static characteristics

Table 6. Static characteristics

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	T _{amb} = 25 °C			T _{amb} = −40 °C to +85 °C		T _{amb} = −40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
74HC138										
V _{IH}	HIGH-level input voltage	V _{CC} = 2.0 V	1.5	1.2	-	1.5	-	1.5	-	V
		V _{CC} = 4.5 V	3.15	2.4	-	3.15	-	3.15	-	V
		V _{CC} = 6.0 V	4.2	3.2	-	4.2	-	4.2	-	V
V _{IL}	LOW-level input voltage	V _{CC} = 2.0 V	-	0.8	0.5	-	0.5	-	0.5	V
		V _{CC} = 4.5 V	-	2.1	1.35	-	1.35	-	1.35	V
		V _{CC} = 6.0 V	-	2.8	1.8	-	1.8	-	1.8	V

Table 6. Static characteristics ...continued

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	T _{amb} = 25 °C			T _{amb} = -40 °C to +85 °C		T _{amb} = -40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
V _{OH}	HIGH-level output voltage	V _I = V _{IH} or V _{IL}								
		I _O = -20 µA; V _{CC} = 2.0 V	1.9	2.0	-	1.9	-	1.9	-	V
		I _O = -20 µA; V _{CC} = 4.5 V	4.4	4.5	-	4.4	-	4.4	-	V
		I _O = -20 µA; V _{CC} = 6.0 V	5.9	6.0	-	5.9	-	5.9	-	V
		I _O = -4.0 mA; V _{CC} = 4.5 V	3.98	4.32	-	3.84	-	3.7	-	V
		I _O = -5.2 mA; V _{CC} = 6.0 V	5.48	5.81	-	5.34	-	5.2	-	V
V _{OL}	LOW-level output voltage	V _I = V _{IH} or V _{IL}								
		I _O = 20 µA; V _{CC} = 2.0 V	-	0	0.1	-	0.1	-	0.1	V
		I _O = 20 µA; V _{CC} = 4.5 V	-	0	0.1	-	0.1	-	0.1	V
		I _O = 20 µA; V _{CC} = 6.0 V	-	0	0.1	-	0.1	-	0.1	V
		I _O = 4.0 mA; V _{CC} = 4.5 V	-	0.15	0.26	-	0.33	-	0.4	V
		I _O = 5.2 mA; V _{CC} = 6.0 V	-	0.16	0.26	-	0.33	-	0.4	V
I _I	input leakage current	V _I = V _{CC} or GND; V _{CC} = 6.0 V	-	-	±0.1	-	±1.0	-	±1.0	µA
I _{OZ}	OFF-state output current	per input pin; V _I = V _{IH} or V _{IL} ; V _O = V _{CC} or GND; other inputs at V _{CC} or GND; V _{CC} = 6.0 V; I _O = 0 A		-	-	±0.5	-	±5.0	-	±10
I _{CC}	supply current	V _I = V _{CC} or GND; I _O = 0 A; V _{CC} = 6.0 V	-	-	8.0	-	80	-	160	µA
C _I	input capacitance		-	3.5	-					pF
74HCT138										
V _{IH}	HIGH-level input voltage	V _{CC} = 4.5 V to 5.5 V	2.0	1.6	-	2.0	-	2.0	-	V
V _{IL}	LOW-level input voltage	V _{CC} = 4.5 V to 5.5 V	-	1.2	0.8	-	0.8	-	0.8	V
V _{OH}	HIGH-level output voltage	V _I = V _{IH} or V _{IL} ; V _{CC} = 4.5 V								
		I _O = -20 µA	4.4	4.5	-	4.4	-	4.4	-	V
		I _O = -4 mA	3.98	4.32	-	3.84	-	3.7	-	V
V _{OL}	LOW-level output voltage	V _I = V _{IH} or V _{IL} ; V _{CC} = 4.5 V								
		I _O = 20 µA	-	0	0.1	-	0.1	-	0.1	V
		I _O = 4.0 mA	-	0.15	0.26	-	0.33	-	0.4	V
I _I	input leakage current	V _I = V _{CC} or GND; V _{CC} = 5.5 V	-	-	±0.1	-	±1.0	-	±1.0	µA
I _{OZ}	OFF-state output current	per input pin; V _I = V _{IH} or V _{IL} ; V _O = V _{CC} or GND; other inputs at V _{CC} or GND; V _{CC} = 5.5 V; I _O = 0 A		-	-	±0.5	-	±5.0	-	±10
I _{CC}	supply current	V _I = V _{CC} or GND; I _O = 0 A; V _{CC} = 5.5 V	-	-	8.0	-	80	-	160	µA

Table 6. Static characteristics ...continued

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	T _{amb} = 25 °C			T _{amb} = -40 °C to +85 °C		T _{amb} = -40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
ΔI_{CC}	additional supply current	$V_I = V_{CC} - 2.1$ V; other inputs at V_{CC} or GND; $V_{CC} = 4.5$ V to 5.5 V; $I_O = 0$ A								
		per input pin; An inputs	-	150	540	-	675	-	735	μ A
		per input pin; \bar{E}_n inputs	-	125	450	-	562.5	-	612.5	μ A
		per input pin; E3 input	-	100	360	-	450	-	490	μ A
C_I	input capacitance		-	3.5	-					pF

10. Dynamic characteristics

Table 7. Dynamic characteristicsVoltages are referenced to GND (ground = 0 V); $C_L = 50$ pF unless otherwise specified; for test circuit see [Figure 8](#).

Symbol	Parameter	Conditions	T _{amb} = 25 °C			T _{amb} = -40 °C to +85 °C		T _{amb} = -40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	

For type 74HC138

t_{pd}	propagation delay	An to \bar{Y}_n ; see Figure 6 ^[1]								
		$V_{CC} = 2.0$ V	-	41	150	-	190	-	225	ns
		$V_{CC} = 4.5$ V	-	15	30	-	38	-	45	ns
		$V_{CC} = 5$ V; $C_L = 15$ pF	-	12	-	-	-	-	-	ns
		$V_{CC} = 6.0$ V	-	12	26	-	33	-	38	ns
		E3 to \bar{Y}_n ; see Figure 6 ^[1]								
		$V_{CC} = 2.0$ V	-	47	150	-	190	-	225	ns
		$V_{CC} = 4.5$ V	-	17	20	-	38	-	45	ns
		$V_{CC} = 5$ V; $C_L = 15$ pF	-	14	-	-	-	-	-	ns
		$V_{CC} = 6.0$ V	-	14	26	-	33	-	38	ns
		\bar{E}_n to \bar{Y}_n ; see Figure 7 ^[1]								
		$V_{CC} = 2.0$ V	-	47	150	-	190	-	225	ns
		$V_{CC} = 4.5$ V	-	17	20	-	38	-	45	ns
		$V_{CC} = 5$ V; $C_L = 15$ pF	-	14	-	-	-	-	-	ns
		$V_{CC} = 6.0$ V	-	14	26	-	33	-	38	ns
t_t	transition time	\bar{Y}_n ; see Figure 6 and Figure 7 ^[2]								
		$V_{CC} = 2.0$ V	-	19	75	-	95	-	110	ns
		$V_{CC} = 4.5$ V	-	7	15	-	19	-	22	ns
		$V_{CC} = 6.0$ V	-	6	13	-	16	-	19	ns
C_{PD}	power dissipation capacitance	$C_L = 50$ pF; $f = 1$ MHz; $V_I = \text{GND to } V_{CC}$ ^[3]	-	67	-	-	-	-	-	pF

Table 7. Dynamic characteristics ...continued

Voltages are referenced to GND (ground = 0 V); $C_L = 50$ pF unless otherwise specified; for test circuit see [Figure 8](#).

Symbol	Parameter	Conditions	T _{amb} = 25 °C			T _{amb} = −40 °C to +85 °C		T _{amb} = −40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
For type 74HCT138										
t _{pd}	propagation delay	An to \overline{Y}_n ; see Figure 6 [1]								
		V _{CC} = 4.5 V	-	20	35	-	44	-	53	ns
		V _{CC} = 5 V; C _L = 15 pF	-	17	-	-	-	-	-	ns
		E3 to \overline{Y}_n ; see Figure 6 [1]								
		V _{CC} = 4.5 V	-	18	40	-	50	-	60	ns
		V _{CC} = 5 V; C _L = 15 pF	-	19	-	-	-	-	-	ns
		\overline{E}_n to \overline{Y}_n ; see Figure 7 [1]								
		V _{CC} = 4.5 V	-	19	40	-	50	-	60	ns
t _t	transition time	V _{CC} = 5 V; C _L = 15 pF	-	19	-	-	-	-	-	ns
		\overline{Y}_n ; see Figure 6 and Figure 7 [2]								
C _{PD}	power dissipation capacitance	V _{CC} = 4.5 V	-	7	15	-	19	-	22	ns
		C _L = 50 pF; f = 1 MHz; V _I = GND to V _{CC} [3]	-	67	-	-	-	-	-	pF

[1] t_{pd} is the same as t_{PLH} and t_{PHL}.

[2] t_t is the same as t_{THL} and t_{TLH}.

[3] C_{PD} is used to determine the dynamic power dissipation (P_D in μW).

$P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \Sigma(C_L \times V_{CC}^2 \times f_o)$ where:

f_i = input frequency in MHz;

f_o = output frequency in MHz;

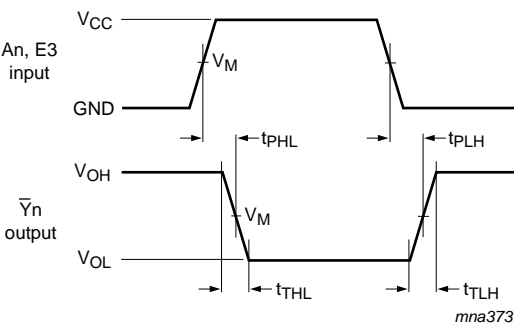
C_L = output load capacitance in pF;

V_{CC} = supply voltage in V;

N = number of inputs switching;

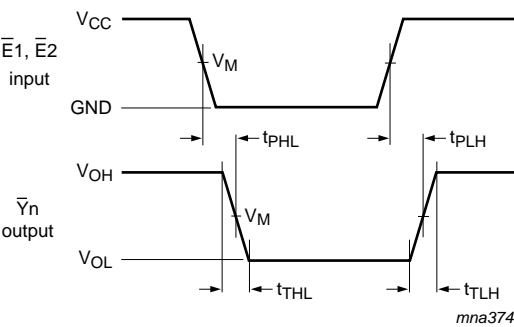
$\Sigma(C_L \times V_{CC}^2 \times f_o)$ = sum of outputs.

11. Waveforms



Measurement points are given in [Table 8](#).
 V_{OL} and V_{OH} are typical voltage output levels that occur with the output load.

Fig 6. Propagation delay input (An) and enable input (E3) to output (\bar{Y}_n) and transition time output (\bar{Y}_n)

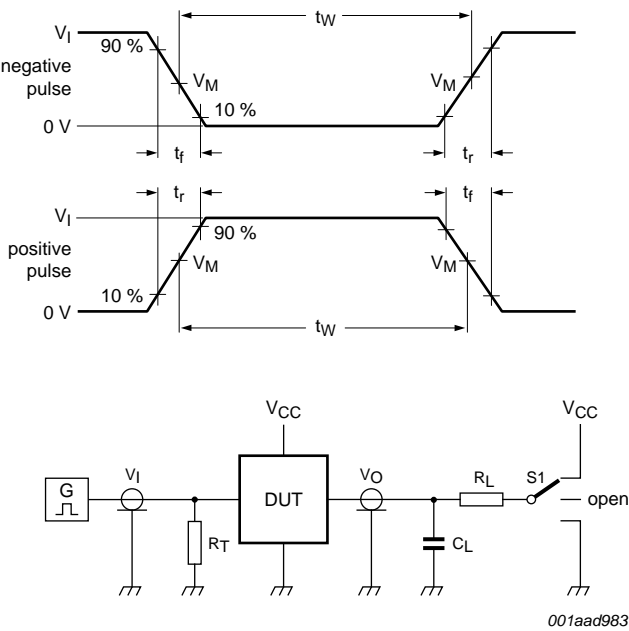


Measurement points are given in [Table 8](#).
 V_{OL} and V_{OH} are typical voltage output levels that occur with the output load.

Fig 7. Propagation delay enable input (\bar{E}_n) to output (\bar{Y}_n) and transition time output (\bar{Y}_n)

Table 8. Measurement points

Type	Input	Output
	V_M	V_M
74HC138	$0.5V_{CC}$	$0.5V_{CC}$
74HCT138	1.3 V	1.3 V



Test data is given in [Table 9](#).

Definitions test circuit:

R_T = Termination resistance should be equal to output impedance Z_o of the pulse generator.

C_L = Load capacitance including jig and probe capacitance.

R_L = Load resistance.

$S1$ = Test selection switch.

Fig 8. Load circuitry for measuring switching times

Table 9. Test data

Type	Input		Load		S1 position		
	V_I	t_r, t_f	C_L	R_L	t_{PHL}, t_{PLH}	t_{PZH}, t_{PHZ}	t_{PZL}, t_{PLZ}
74HC138	V_{CC}	6 ns	15 pF, 50 pF	1 k Ω	open	GND	V_{CC}
74HCT138	3 V	6 ns	15 pF, 50 pF	1 k Ω	open	GND	V_{CC}

12. Package outline

DIP16: plastic dual in-line package; 16 leads (300 mil)

SOT38-4

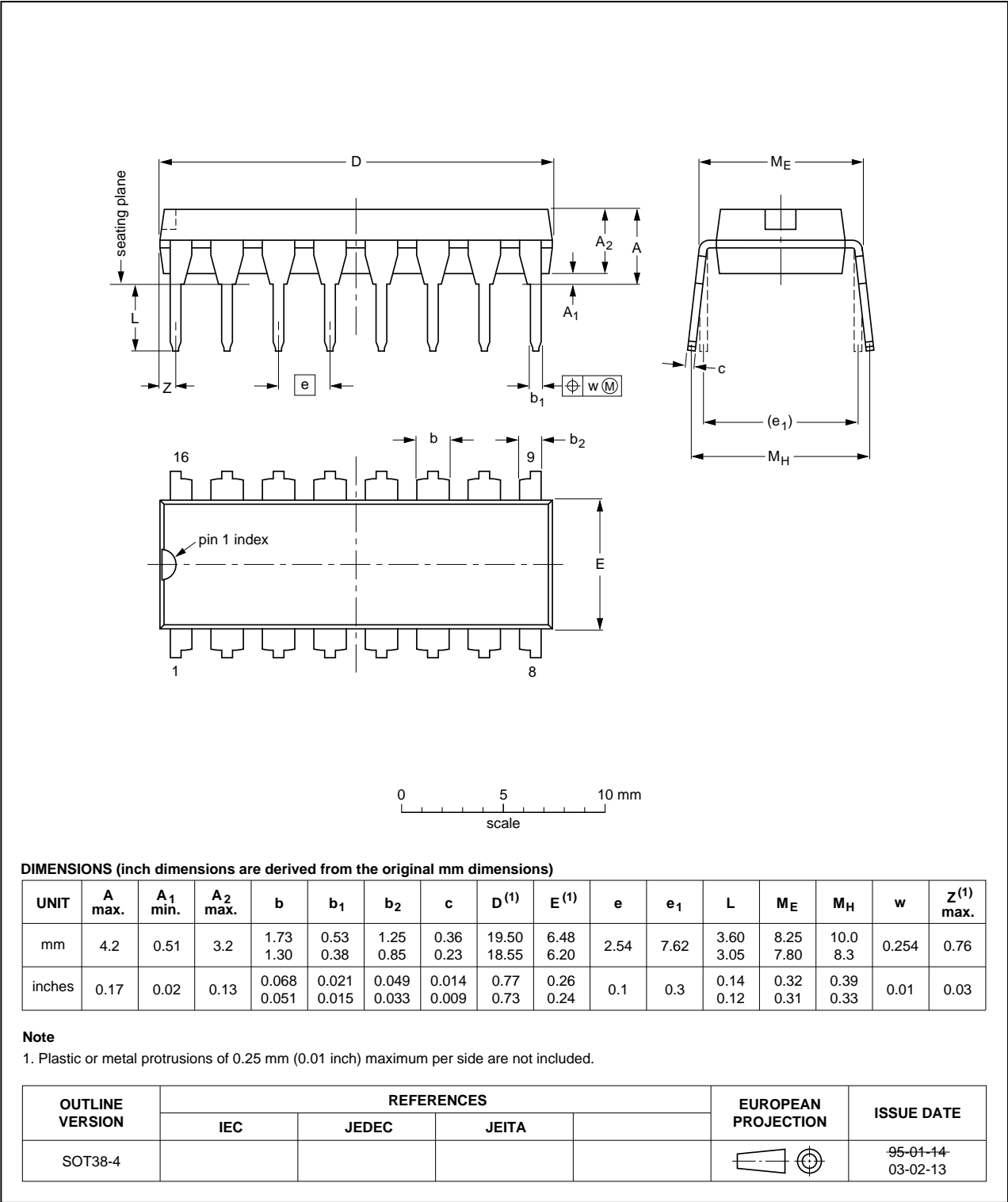
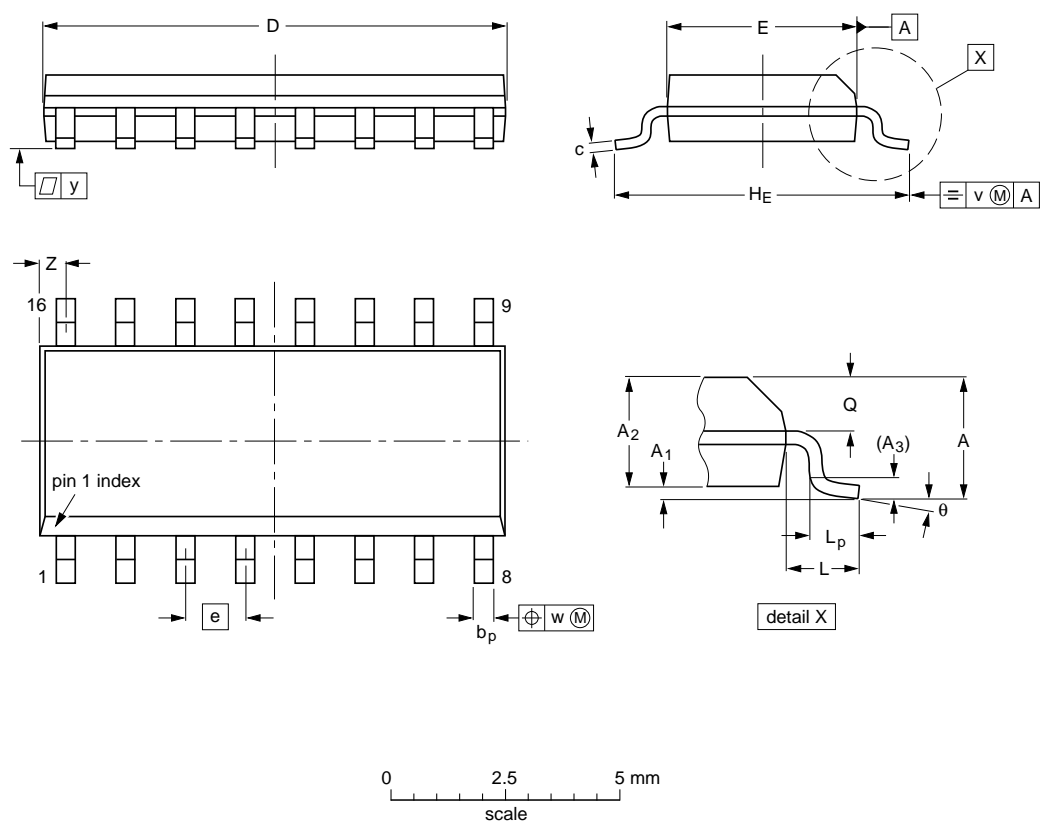


Fig 9. Package outline SOT38-4 (DIP16)

SO16: plastic small outline package; 16 leads; body width 3.9 mm

SOT109-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽¹⁾	e	H _E	L	L _p	Q	v	w	y	Z ⁽¹⁾	θ
mm	1.75	0.25 0.10	1.45 1.25	0.25	0.49 0.36	0.25 0.19	10.0 9.8	4.0 3.8	1.27	6.2 5.8	1.05	1.0 0.4	0.7 0.6	0.25	0.25	0.1	0.7 0.3	8° 0°
inches	0.069	0.010 0.004	0.057 0.049	0.01	0.019 0.014	0.0100 0.0075	0.39 0.38	0.16 0.15	0.05	0.244 0.228	0.041	0.039 0.016	0.028 0.020	0.01	0.01	0.004	0.028 0.012	

Note

1. Plastic or metal protrusions of 0.15 mm (0.006 inch) maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT109-1	076E07	MS-012				99-12-27 03-02-19

Fig 10. Package outline SOT109-1 (SO16)

TSSOP16: plastic thin shrink small outline package; 16 leads; body width 4.4 mm

SOT403-1

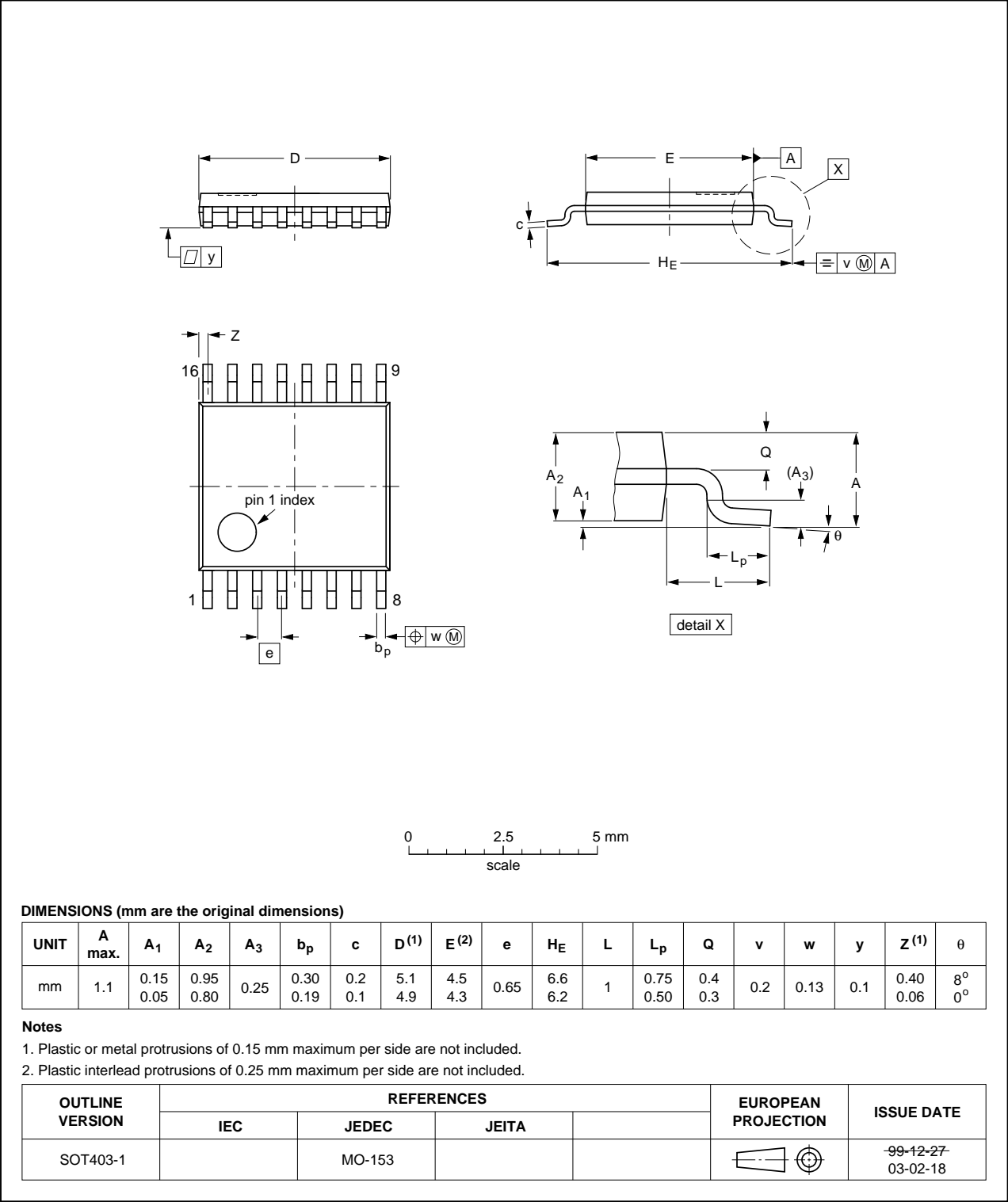


Fig 11. Package outline SOT403-1 (TSSOP16)

SSOP16: plastic shrink small outline package; 16 leads; body width 5.3 mm

SOT338-1

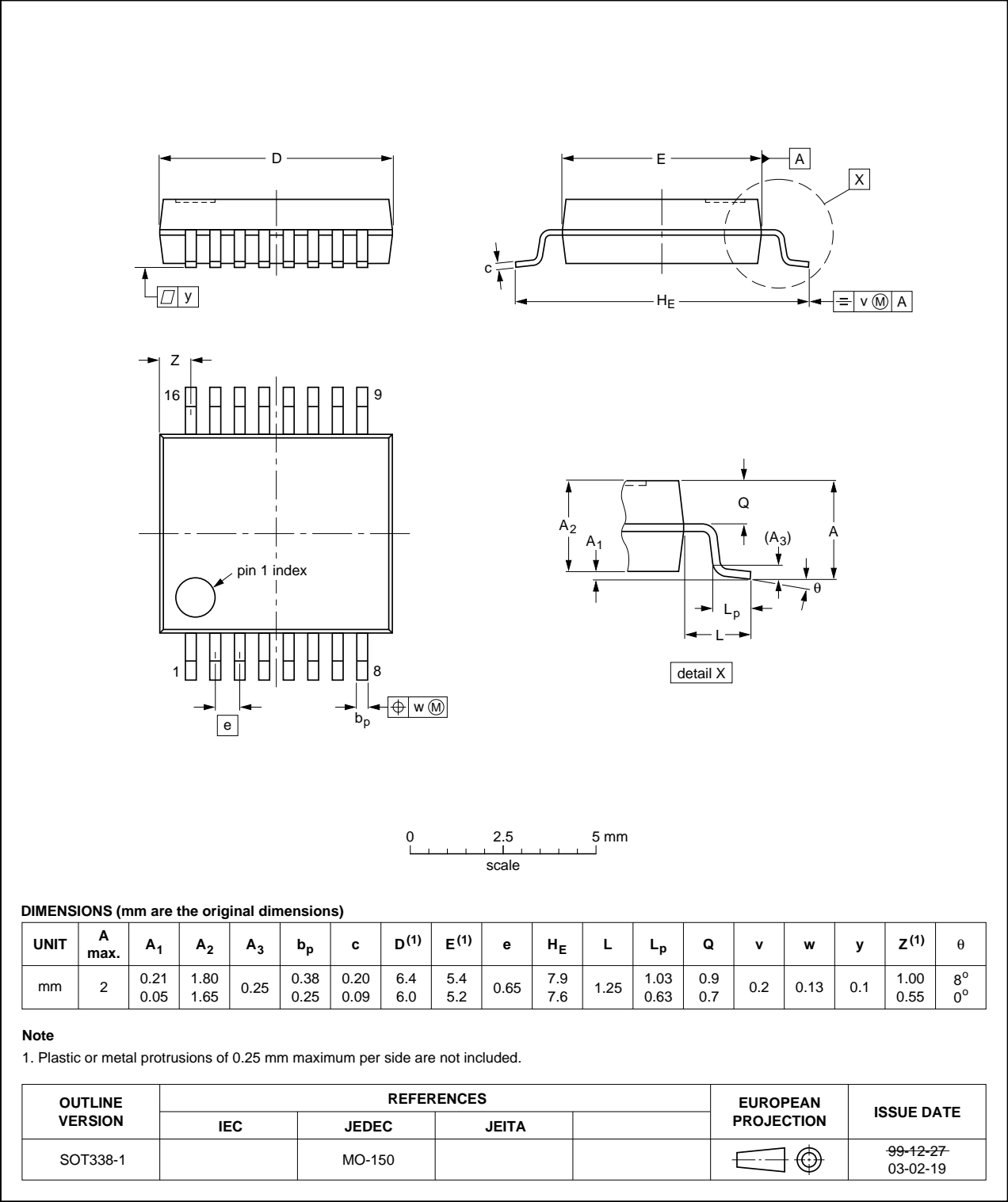


Fig 12. Package outline SOT338-1 (SSOP16)

DHVQFN16: plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads;
16 terminals; body 2.5 x 3.5 x 0.85 mm

SOT763-1

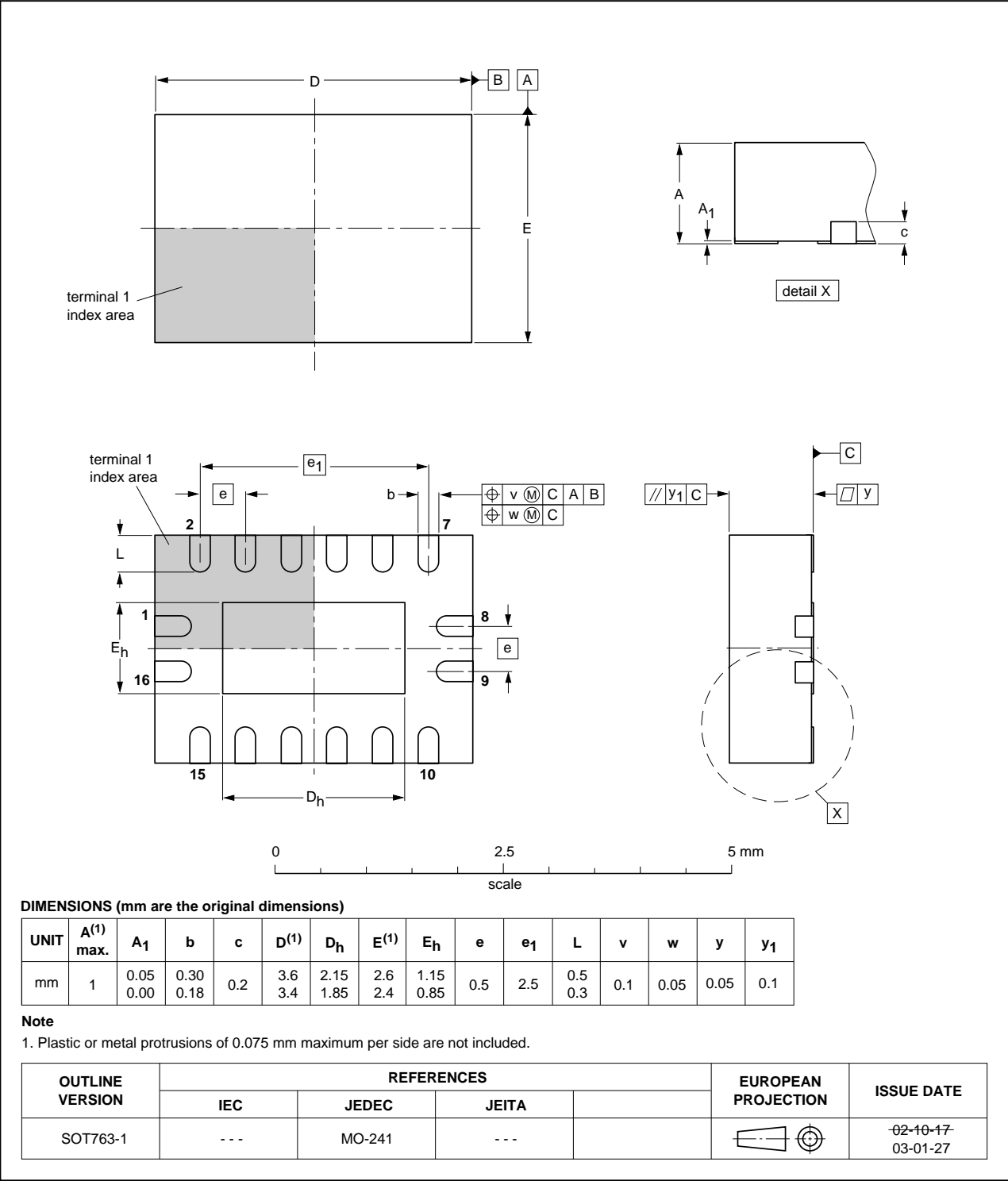


Fig 13. Package outline SOT763-1 (DHVQFN16)

13. Abbreviations

Table 10. Abbreviations

Acronym	Description
CMOS	Complementary Metal Oxide Semiconductor
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
LSTTL	Low-power Schottky Transistor-Transistor Logic
MM	Machine Model

14. Revision history

Table 11. Revision history

Document ID	Release date	Data sheet status	Change notice	Doc. number	Supersedes
74HC_HCT138 v.4	20120627	Product data sheet	-	-	74HC_HCT138 v.3
Modifications:	<ul style="list-style-type: none">• The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors.• Legal texts have been adapted to the new company name where appropriate.• SOT38-1 changed to SOT38-4.				
74HC_HCT138 v.3	20051223	Product data sheet	-	-	74HC_HCT138_CNV v.2
Modifications:	<ul style="list-style-type: none">• The format of this data sheet has been redesigned to comply with the new presentation and information standard of Philips Semiconductors.• Section 3 "Ordering information", Section 5 "Pinning information" and Section 12 "Package outline": Added DHVQFN package information• Section 9 "Static characteristics": Added from the family specification				
74HC_HCT138_CNV v.2	19970827	Product specification	-	-	-

15. Legal information

15.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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